Company Contact:

Chuck Byer, Z-Plane, Inc.

415.309.2647   650.324.4175 fax   e-mail: ccbyer@z-planeinc.com

Z-Plane Inc. Presents at IEEE Technology Exploration Forum

Palo Alto, California, June 14, 2011 – Z-Plane Inc. an innovative high-speed electronic packaging and interconnection technology company, gave a presentation on June 14 at the 2011 IEEE Technology Exploration Forum (TEF), at the Techmart in San Jose CA, hosted by the Ethernet Alliance.

The Ethernet Alliance, the industry organization that promotes implementation of Ethernet technology, furthered its educational mission on June 14, 2011 with its latest Technology Exploration Forum (TEF). The subject of the forum, "Next Generation 100GbE Interconnect Specifications," was particularly timely according to John D'Ambrosia, chair of the Ethernet Alliance – as well as the leader of the IEEE's 802.3ba standards effort, which produced the 40- and 100-Gigabit Ethernet specifications.

The forum brought together Ethernet industry experts to discuss and explore solutions for 100 GBE. The Z-Plane presentation was given by Timothy Lemke, CDO, and was entitled, "Innovative 100G Architecture." Z-Plane presented and discussed its new solution for high-speed telecom and datacom server backplanes.

About Z-Plane, Inc.:

Founded in late 2008, Z-Plane, Inc. is a technology-based high-speed electronic packaging and interconnection technology company, which was established to develop, market, manufacture and license high-speed backplane packaging and interconnection solutions. Z-Plane is committed to providing new packaging technologies for high-speed telecommunications and computing equipment, including routers, servers, and switches with data rates from 40 Gb/sec/ch (40 Gigabits/second/channel or 40G) to more than 100G. The Z-Plane packaging technology focuses on chip-to-chip interactions and includes high-speed backplane design, backplane connectors, and daughter card design. www.z-planeinc.com